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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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10/573,628

03/28/2006

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01/10/2008

EXAMINER

AURORA, REENA

ART UNIT

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2862

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PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

DETAILED ACTION

This communication is in response to amendment received on 10/18/07.

Claims 1 – 19 are presented for examination.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1 – 19 are rejected under 35 U.S.C. 102(b) as being anticipated by Buselmeier et al. (DE4218793).

As to claims 1 – 14, Buselmeier et al. (hereinafter Buselmeier) discloses a sensor comprising a housingless flip chip integrated circuit (1) is mounted on a basic component (6) provided with conductor tracks (2 - 4) and embodied as an MID (Molded Interconnect Device) component, enclosed jointly with the conductor tracks (2 - 4) and optionally further elements by a diamagnetic or paramagnetic covering and directly connected to terminal points (2 - 4) of conductor tracks (2 - 4).

As to claims 15 - 19, Buselmeier discloses a sensor wherein casting or injection molding of thermoplastic, a basic component (6) is produced; that conductor tracks (2 - 4) for the connection to a housingless integrated circuit (1) are mounted on the basic component (6); that the integrated circuit (1) is joined in wireless fashion by the flip-chip technique directly to the conductor tracks (2 - 4), and the arrangement is then sheathed

at least partly with an outer encapsulation in a further casting or injection molding process (Note Abstract).

Response to Arguments

Applicant's arguments with respect to claims 1 - 19 have been considered but are moot in view of the new ground(s) of rejection.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Reena Aurora whose telephone number is 571-272-2263. The examiner can normally be reached on Monday - Friday, 7:00 - 3:30.


If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, P. Assouad can be reached on 571-272-2210. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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